Record No: 2162
Control No: 125

RoHS and Lead Free Certificate of Compliance

PART NUMBER	DESCRIPTION	ROHS	Y	Always Compliant:	
45-1403	CABLE, USB (A) / (B) 3M	LEAD FREE		Compliant Date:	

This document certifies that the above stated GC Electronics product is compliant with the **Directive 2002/95/EC of the European Parliament on the Restriction of Hazardous Substances in electrical and electronics equipment (RoHS Directives)**. The stated product is deemed to be concentration values issued by the European Union Technical Adaptation Committee (TAC) as shown below.

Substance	Maximum Allowed	Actual Concentration	Substance	Maximum Allowed	Actual Concentration
LEAD - Pb	0.1%	<0.1%	Hexavalent Chromium - Cr (VI)	0.1%	<0.1%
Mercury - Hg	0.1%	<0.1%	Polybrominated - PBB	0.1%	<0.1%
Cadmium - Cd	0.01%	<0.01%	Polybrominated diphenyl ethers - PBDB	0.1%	<0.1%

RoHS exemptions.

Applications of lead, mercury, cadmium and hexavalent chromium, which are exempted from the requirements of Article 4(1) of the RoHS Directive.

- Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.
- Mercury in straight fluorescent lamps for general purposes not exceeding:
  — halophosphate 10 mg
  — triphosphate with normal lifetime 5 mg
  — triphosphate with long lifetime 8 mg
- Mercury in straight fluorescent lamps for special purposes
- Mercury in other lamps not specifically mentioned in this Annex
- Lead in glass of cathode ray tubes, electronic components and fluorescent tubes
- Lead as an alloying element in steel containing up to 0,35 % lead by weight, aluminium containing up to 0,4 % lead by weight and as a copper alloy containing up to 4 % lead by weight
- — lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
  — lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications
  — lead in electronic ceramic parts (e.g. piezoelectronic devices)
- Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (1) amending Directive 76/769/EEC (2) relating to restrictions on the marketing and use of certain dangerous substances and preparations
- Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators
- a DecaBDE in polymeric applications
- b Lead in lead-bronze bearing shells and bushes
- 0 Lead used in compliant pin connector systems
- 1 Lead as a coating material for the thermal conduction module c-ring
- 2 Lead and cadmium in optical and filter glass
- 3 Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight
- 4 Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

Signed:

Eric Smith - Product Manager GC Electronics